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SLVS004H-APRIL 1979-REVISED OCTOBER 2011

3-TERMINAL ADJUSTABLE REGULATOR

Check for Samples: TL317

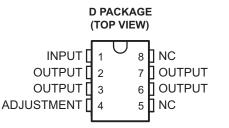
FEATURES

- Output Voltage Range Adjustable From 1.25 V to 32 V When Used With an External Resistor Divider
- Output Current Capability of 100 mA
- Input Regulation Typically 0.01% Per Input-Voltage Change
- Output Regulation Typically 0.5%
- Ripple Rejection Typically 80 dB

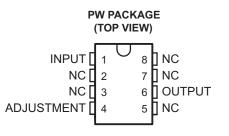
DESCRIPTION

The TL317 is an adjustable three-terminal positive-voltage regulator capable of supplying 100 mA over an output-voltage range of 1.25 V to 32 V. It is exceptionally easy to use and requires only two external resistors to set the output voltage.

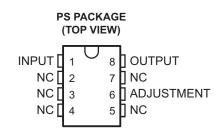
In addition to higher performance than fixed regulators, this regulator offers full overload protection available only in integrated circuits. Included on the chip are current-limiting and thermal-overload protection. All overload-protection circuitry remains fully functional, even when Normally, ADJUSTMENT is disconnected. no capacitors are needed unless the device is situated far from the input filter capacitors, in which case an input bypass is needed. An optional output capacitor can be added to improve transient response. ADJUSTMENT can be bypassed to achieve very high ripple rejection, which is difficult to achieve with standard three-terminal regulators.



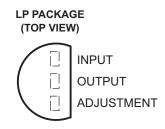
NC No internal connection OUTPUT terminals are all internally connected.



NC No internal connection



NC No internal connection



In addition to replacing fixed regulators, the TL317 regulator is useful in a wide variety of other applications. Since the regulator is floating and sees only the input-to-output differential voltage, supplies of several hundred volts can be regulated as long as the maximum input-to-output differential is not exceeded. Its primary application is that of a programmable output regulator, but by connecting a fixed resistor between ADJUSTMENT and OUTPUT, this device can be used as a precision current regulator. Supplies with electronic shutdown can be achieved by clamping ADJUSTMENT to ground, programming the output to 1.2 V, where most loads draw little current.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



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The TL317C is characterized for operation over the virtual-junction temperature range of 0°C to 125°C. The TL317 is characterized for operation over the virtual-junction temperature range of –20°C to 125°C.

ORDERING INFORMATION

| TJ | PACKAGE ⁽¹⁾ | | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|----------------|------------------------|--------------|--------------------------|---------------------|
| | | Tube of 75 | TL317CD | TI 0470 |
| | SOIC (D) | Reel of 2500 | TL317CDR | |
| 000 10 40500 | | Bulk of 1000 | TL317CLP | TI 0470 |
| 0°C to 125°C | TO-226 / TO-92 (LP) | Reel of 2000 | TL317CLPR | TL317C |
| | | Tube of 150 | TL317CPW | T047 |
| | TSSOP (PW) | Reel of 2000 | TL317CPWR | T317 |
| | TO-226 / TO-92 (LP) | Bulk of 1000 | TL317LP | TL317 |
| –20°C to 125°C | | Tube of 80 | TL317PS | T047 |
| | SOP (PS) | Reel of 2000 | TL317PSR | T317 |

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

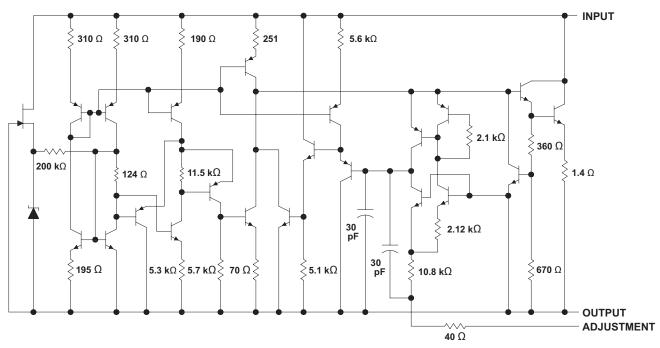


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TL317

SCHEMATIC



A. All component values shown are nominal.

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

| | | VALUE | UNIT |
|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------|------------|------|
| Input-to-output differential voltage, V _I – V _O | | 35 | V |
| | D package | 97 | °C/W |
| $\mathbf{P}_{\mathbf{r}}$, $\mathbf{P}_{\mathbf{r}}$ | LP package | 140 | °C/W |
| Package thermal impedance, $\theta_{JA}^{(2)(3)}$: | PS package | 95 | °C/W |
| | PW package | 149 | °C/W |
| Operating virtual junction temperature, T _J | | 150 | °C |
| Storage temperature range, T _{stg} | | -65 to 150 | °C |

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient

(2) temperature is $P_D = (T_J(max) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.

The package thermal impedance is calculated in accordance with JESD 51-7. (3)

RECOMMENDED OPERATING CONDITIONS

| | | | MIN | MAX | UNIT |
|-----------------|----------------------------------------------------------------------|--------|-----|-----|------|
| $V_{I} - V_{O}$ | V _I – V _O Input-to-output voltage differential | | | | V |
| I _O | Output current | 2.5 | 100 | mA | |
| - | | TL317C | 0 | 125 | °C |
| ۱ _J | Operating virtual-junction temperature | -20 | 125 | °C | |



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ELECTRICAL CHARACTERISTICS

over recommended operating virtual-junction temperature range (unless otherwise noted)

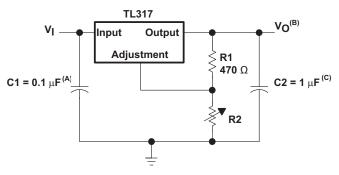
| PARAMETER | TEST CO | NDITIONS ⁽¹⁾ | MIN | TYP | MAX | UNIT |
|-----------------------------------------------|--------------------------------------------------------------------------|------------------------------------|-----|------|------|------|
| Input voltage regulation (2) | | $T_J = 25^{\circ}C$ | | 0.01 | 0.02 | %V |
| Input voltage regulation ⁽²⁾ | $V_{I} - V_{O} = 5 V \text{ to } 35 V$ | $I_{O} = 2.5$ mA to 100 mA | | 0.02 | 0.05 | %V |
| | V _O = 10 V, | f = 120 Hz | | 65 | | |
| Ripple regulation | V _O = 10 V, 10-µF capacitor between ground | ADJUSTMENT and | 66 | 80 | | dB |
| Output voltage regulation | $V_1 = 5 V \text{ to } 35 V,$ | $V_0 \le 5 V$ | | 25 | | mV |
| | $I_0 = 2.5 \text{ mA to } 100 \text{ mA},$ $T_J = 25^{\circ}\text{C}$ | $V_{O} \ge 5 V$ | | 5 | | mV/V |
| | $V_1 = 5 V \text{ to } 35 V,$ | $V_0 \le 5$ | | 50 | | mV |
| | $I_0 = 2.5 \text{ mA to } 100 \text{ mA}$ | $V_{O} \ge 5 V$ | | 10 | | mV/V |
| Output voltage change with temperature | $T_J = 0^{\circ}C$ to $125^{\circ}C$ | | | 10 | | mV/V |
| Output voltage long-term drift | After 1000 hours at $T_J =$ | 125°C and $V_I - V_O = 35 V$ | | 3 | 10 | mV/V |
| Output noise voltage | f = 10 Hz to 10 kHz, | $T_J = 25^{\circ}C$ | | 30 | | μV/V |
| Minimum output current to maintain regulation | $V_{I} - V_{O} = 35$ | | | 1.5 | 2.5 | mA |
| Peak output current | $V_{I} - V_{O} \le 35 V$ | | 100 | 200 | | mA |
| ADJUSTMENT current | | | | 50 | 100 | μA |
| Change in ADJUSTMENT current | $V_{I} - V_{O} = 2.5 \text{ V to } 35 \text{ V},$ | I _O = 2.5 mA to 100 mA | | 0.2 | 5 | μA |
| Reference voltage (output to ADJUSTMENT) | $V_I - V_O = 5 V \text{ to } 35 V,$ P ≤ rated dissipation | I _O = 2.5 mA to 100 mA, | 1.2 | 1.25 | 1.3 | V |

(1) Unless otherwise noted, these specifications apply for the following test conditions: V_I – V_O = 5 V and I_O = 40 mA. Pulse-testing techniques must be used that maintain the junction temperature as close to the ambient temperature as possible. All characteristics are measured with a 0.1-μF capacitor across the input and a 1-μF capacitor across the output.

(2) Input voltage regulation is expressed here as the percentage change in output voltage per 1-V change at the input.



APPLICATION INFORMATION



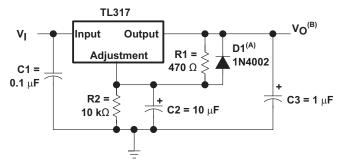
- A. Use of an input bypass capacitor is recommended if regulator is far from the filter capacitors.
- B. Output voltage is calculated from the equation:

$$V_{\rm o} = V_{\rm ref} \left(1 + \frac{R2}{R1} \right)$$

where: V_{ref} equals the difference between OUTPUT and ADJUSTMENT voltages (~1.25 V).

C. Use of an output capacitor improves transient response, but is optional.

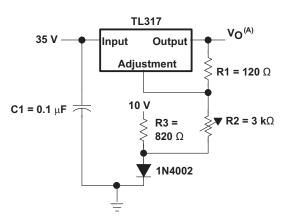
Figure 1. Adjustable Voltage Regulator



A. D1 discharges C2 if output is shorted to ground.

B. Use of an output capacitor improves transient response, but is optional.

Figure 3. Regulator Circuit With Improved Ripple Rejection



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A. Output voltage is calculated from the equation: V_{-1} $\begin{pmatrix} 1 \\ R^2 + R^3 \end{pmatrix}_{10}$ V_{-1}

$$V_{o} = V_{ref} \left(1 + \frac{12.116}{R1} \right) - 10 V$$

where: V_{ref} equals the difference between OUTPUT and ADJUSTMENT voltages (~1.25 V).

Figure 2. 0-V to 30-V Regulator Circuit

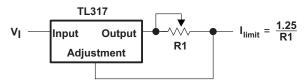


Figure 4. Precision Current-Limiter Circuit

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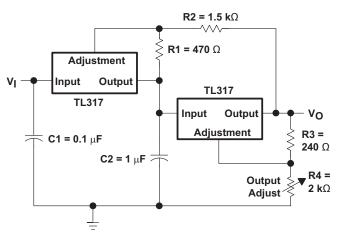
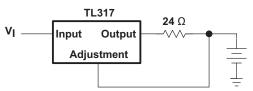


Figure 5. Tracking Preregulator Circuit



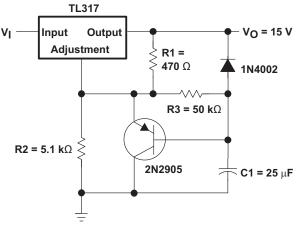


Figure 6. Slow-Turnon 15-V Regulator Circuit

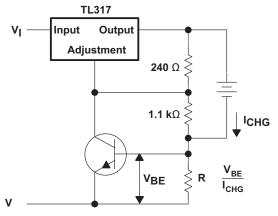


Figure 7. 50-mA Constant-Current Battery-Charger Circuit

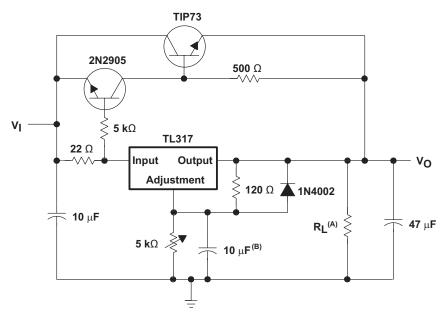
Figure 8. Current-Limited 6-V Charger

APPLICATION INFORMATION



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APPLICATION INFORMATION



A. Minimum load current is 30 mA.

B. Optional capacitor improves ripple rejection.

Figure 9. High-Current Adjustable Regulator

Product Folder Link(s): TL317

REVISION HISTORY

| Cł | Changes from Revision G (September 2009) to Revision H | | | | | | | |
|----|---------------------------------------------------------------------------------------------------|---|--|--|--|--|--|--|
| • | Changed datasheet format from QuickSilver to DocZone. | 1 | | | | | | |
| • | Changed low end output voltage range from 1.2 V to 1.25. | 1 | | | | | | |
| • | Changed low end output voltage range from 1.2 V to 1.25. | 1 | | | | | | |
| • | Added MIN value of 2.5 V for $V_I - V_O$ parameter in the Recommended Operating Conditions table. | 3 | | | | | | |

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17-Aug-2012

PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/ Ball Finish | MSL Peak Temp ⁽³⁾ | Samples (Requires Login) |
|------------------|-----------------------|--------------|--------------------|------|-------------|----------------------------|----------------------|------------------------------|-----------------------------|
| TL317CD | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| TL317CDE4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| TL317CDG4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| TL317CDR | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| TL317CDRE4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| TL317CDRG4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| TL317CLP | ACTIVE | TO-92 | LP | 3 | 1000 | Pb-Free (RoHS) | CU SN | N / A for Pkg Type | |
| TL317CLPE3 | ACTIVE | TO-92 | LP | 3 | 1000 | Pb-Free (RoHS) | CU SN | N / A for Pkg Type | |
| TL317CLPR | ACTIVE | TO-92 | LP | 3 | 2000 | Pb-Free (RoHS) | CU SN | N / A for Pkg Type | |
| TL317CLPRE3 | ACTIVE | TO-92 | LP | 3 | 2000 | Pb-Free (RoHS) | CU SN | N / A for Pkg Type | |
| TL317CPW | ACTIVE | TSSOP | PW | 8 | 150 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| TL317CPWE4 | ACTIVE | TSSOP | PW | 8 | 150 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| TL317CPWG4 | ACTIVE | TSSOP | PW | 8 | 150 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| TL317CPWR | ACTIVE | TSSOP | PW | 8 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| TL317CPWRE4 | ACTIVE | TSSOP | PW | 8 | | TBD | Call TI | Call TI | |
| TL317CPWRG4 | ACTIVE | TSSOP | PW | 8 | | TBD | Call TI | Call TI | |
| TL317PS | ACTIVE | SO | PS | 8 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| TL317PSE4 | ACTIVE | SO | PS | 8 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| TL317PSG4 | ACTIVE | SO | PS | 8 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |

17-Aug-2012

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/ Ball Finish | MSL Peak Temp ⁽³⁾ | Samples (Requires Login) |
|------------------|-----------------------|--------------|--------------------|------|-------------|----------------------------|----------------------|------------------------------|-----------------------------|
| TL317PSR | ACTIVE | SO | PS | 8 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| TL317PSRE4 | ACTIVE | SO | PS | 8 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| TL317PSRG4 | ACTIVE | SO | PS | 8 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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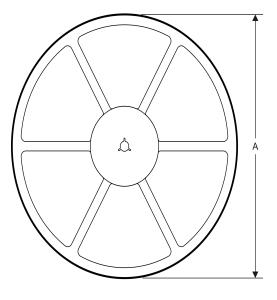
PACKAGE MATERIALS INFORMATION

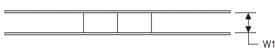
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TAPE AND REEL INFORMATION

REEL DIMENSIONS

TEXAS INSTRUMENTS





SOIC

TSSOP

SO

TAPE AND REEL INFORMATION

TL317CDR

TL317CPWR

TL317PSR

TAPE DIMENSIONS



| A0 | Dimension designed to accommodate the component width |
|----|-----------------------------------------------------------|
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

B0

(mm)

5.2

3.6

6.6

6.4

7.0

8.2

K0

(mm)

2.1

1.6

2.5

P1

(mm)

8.0

8.0

12.0

w

(mm)

12.0

12.0

16.0

Pin1

Quadrant

Q1

Q1

Q1

| *All dimensions are nominal | | | | | |
|-----------------------------|------------------------|--|--------------------------|--------------------------|------------|
| Device | Package Drawing | | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) |

8

8

8

2500

2000

2000

330.0

330.0

330.0

12.4

12.4

16.4

D

PW

PS

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

17-Aug-2012



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|-----------|--------------|-----------------|------|------|-------------|------------|-------------|
| TL317CDR | SOIC | D | 8 | 2500 | 340.5 | 338.1 | 20.6 |
| TL317CPWR | TSSOP | PW | 8 | 2000 | 367.0 | 367.0 | 35.0 |
| TL317PSR | SO | PS | 8 | 2000 | 367.0 | 367.0 | 38.0 |

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

PS (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE

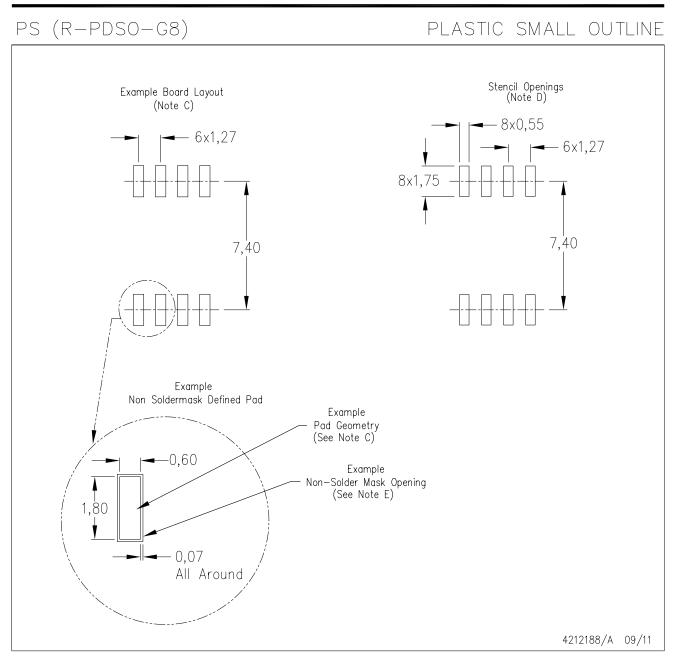


A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.





NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

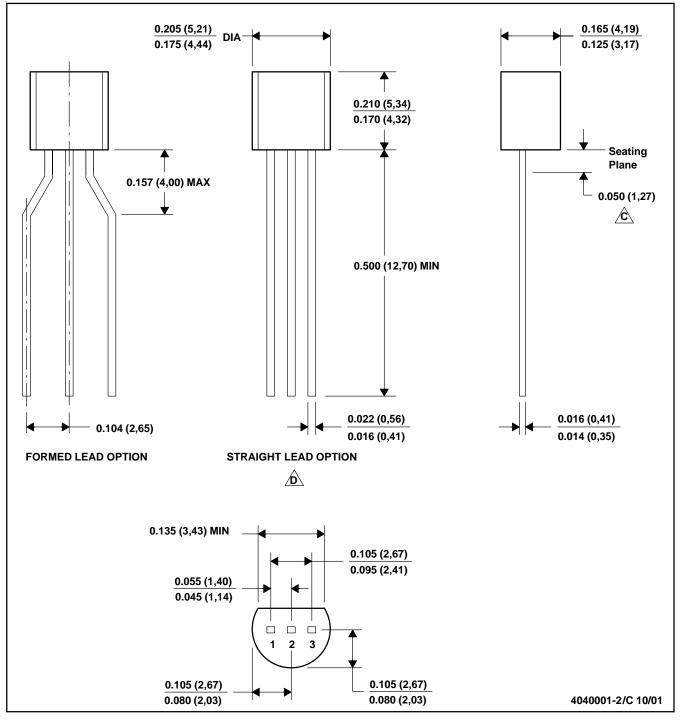


MECHANICAL DATA

MSOT002A - OCTOBER 1994 - REVISED NOVEMBER 2001

LP (O-PBCY-W3)

PLASTIC CYLINDRICAL PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

 \underline{c} Lead dimensions are not controlled within this area

D. FAlls within JEDEC TO -226 Variation AA (TO-226 replaces TO-92)

E. Shipping Method:

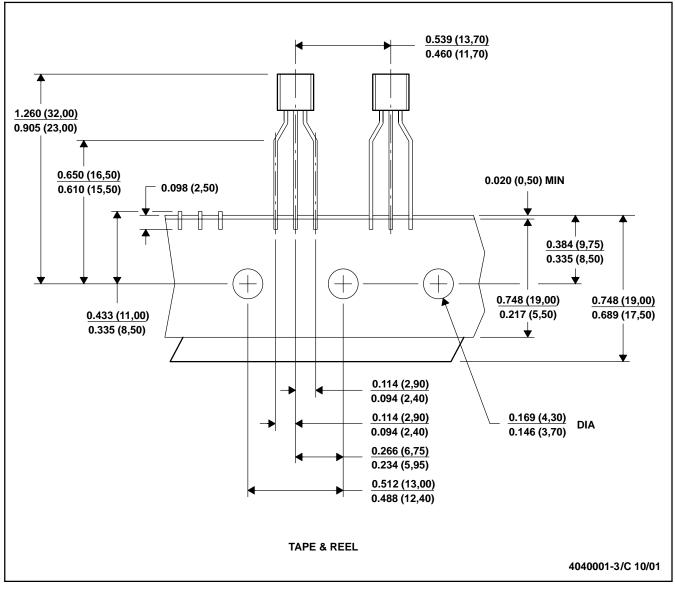
Straight lead option available in bulk pack only.

Formed lead option available in tape & reel or ammo pack.

MSOT002A - OCTOBER 1994 - REVISED NOVEMBER 2001

LP (O-PBCY-W3)

PLASTIC CYLINDRICAL PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

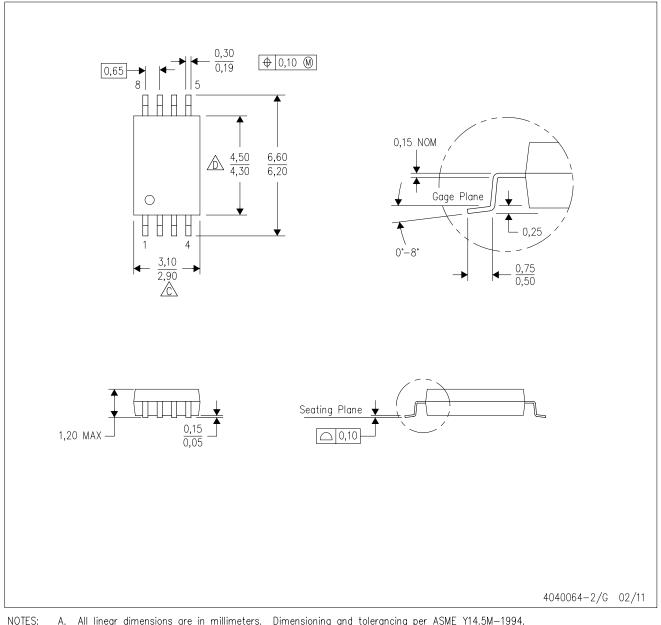
B. This drawing is subject to change without notice.

C. Tape and Reel information for the Format Lead Option package.



PW (R-PDSO-G8)

PLASTIC SMALL OUTLINE



Α. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994. Ŗ. This drawing is subject to change without notice.

🖄 Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.

Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.

E. Falls within JEDEC MO-153



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